

AN 82:128418 HCA  
TI Copper-thallium alloys with good heat resistance and electrical conductivity  
IN Sakamoto, Mutsuo; Sotomura, Takashi  
PA Furukawa Electric Co., Ltd.  
SO Japan., 3 pp.  
CODEN: JAXXAD

DT Patent  
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 49007777	B4	19740222	JP 1970-87320	19701005
AB	The Cu alloy contains Tl 0.005-0.08 and O >0.0005%. The alloy is cooled from 900-1050.degree. at >5 .degree.C/min, hot worked at >750.degree., cold worked, and annealed at >600.degree..				

AN 98:202779 HCA  
TI Amorphous copper-silver films with high stability  
AU Reda, I. M.; Hafner, J.; Pongratz, P.; Wagendristel, A.; Bangert, H.;  
Bhat, P. K.  
CS Int. Cent. Theor. Phys., Trieste, Italy  
SO Report (1982), IC-82/62, 30 pp. Avail.: INIS  
From: INIS Atomindex 1983, 14(3), Abstr. No. 723484  
DT Report  
LA English  
AB Films produced by quenching Cu-Ag vapor onto cooled  
substrates at liq. N temp. were investigated by using electron microscopy,  
electron diffraction, and elec. resistivity measurements. At 30-70 at.%  
Cu, the as-quenched films were amorphous. At 35-63 at.%  
Cu, the amorphous phase was stable above room temp. with a max.  
crystn. temp. of 381 K at 47.5 at.% Cu. Crystn. results in  
formation of a supersatd. fcc. solid soln. which decomp. in a 2nd crystn.  
step. The effect of deposition rate, film thickness, temp.,  
substrate surface, and compn. on the transition temps. was detd. A  
comparative study of amorphous phase formation in other Cu  
alloys is presented.